





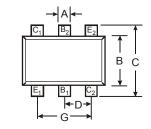
DUAL NPN SMALL SIGNAL SURFACE MOUNT TRANSISTOR

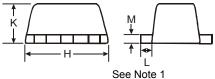
Features

- **Epitaxial Planar Die Construction**
- Ideal for Low Power Amplification and Switching
- Ultra-Small Surface Mount Package
- Lead Free By Design/RoHS Compliant (Note 3)
- "Green" Device (Note 4 and 5)

Mechanical Data

- Case: SOT-563
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Finish Matte Tin annealed over Alloy 42 leadframe. Solderable per MIL-STD-202, Method 208
- Terminal Connections: See Diagram
- Terminals: Lead bearing terminal plating available. See Ordering information Page 3
- Marking Information: KAP, See Page 3
- Ordering Information: See Page 3
- Weight: 0.003 grams (approximate)







SOT-563								
Dim	Min	Max	Тур					
Α	0.15	0.30	0.25					
В	1.10	1.25	1.20					
С	1.55	1.70	1.60					
D	0.50							
G	0.90	1.10	1.00					
Н	1.50	1.60						
K	0.56	0.60	0.60					
L	0.10	0.30	0.20					
M	0.10	0.18	0.11					
All Dimensions in mm								

Maximum Ratings @TA = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit	
Collector-Base Voltage	V _{CBO}	60	V	
Collector-Emitter Voltage	V _{CEO}	40	V	
Emitter-Base Voltage	V _{EBO}	6.0	V	
Collector Current - Continuous	I _C	200	mA	
Power Dissipation (Note 2)	Pd	200	mW	
Thermal Resistance, Junction to Ambient	$R_{ heta JA}$	625	°C/W	
Operating and Storage Temperature Range	T _j , T _{STG}	-55 to +150	°C	

Notes:

- 1. Package is non-polarized. Parts may be on reel in orientation illustrated, 180° rotated, or mixed (both ways).
- Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.
- 3. No purposefully added lead.
- Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.

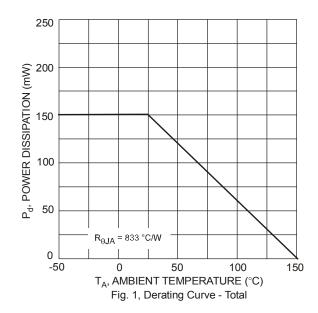
 Product manufactured with Date Code UO (week 40, 2007) and newer are built with Green Molding Compound. Product manufactured prior to Date Code UO are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.

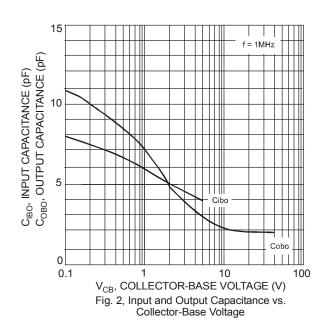


Electrical Characteristics @TA = 25°C unless otherwise specified

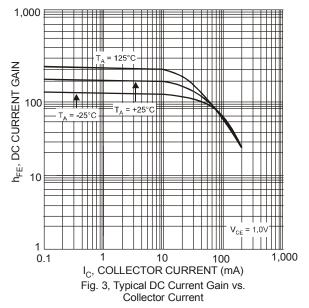
Characteristic	Symbol	l Min Max Unit		Unit	Test Condition		
OFF CHARACTERISTICS (Note 6)							
Collector-Base Breakdown Voltage	V _{(BR)CBO}	60	_ V		$I_C = 10\mu A, I_E = 0$		
Collector-Emitter Breakdown Voltage	V _{(BR)CEO}	40		V	$I_C = 1.0 \text{mA}, I_B = 0$		
Emitter-Base Breakdown Voltage	V _{(BR)EBO}	5.0	_	V	$I_E = 10\mu A, I_C = 0$		
Collector Cutoff Current	I _{CEX}	_	50	nA	V _{CE} = 30V, V _{EB(OFF)} = 3.0V		
Base Cutoff Current	I _{BL}	_	50	nA	V _{CE} = 30V, V _{EB(OFF)} = 3.0V		
ON CHARACTERISTICS (Note 6)							
DC Current Gain	h _{FE}	40 70 100 60 30	 300 	l	$I_C = 100\mu A, V_{CE} = 1.0V$ $I_C = 1.0mA, V_{CE} = 1.0V$ $I_C = 10mA, V_{CE} = 1.0V$ $I_C = 50mA, V_{CE} = 1.0V$ $I_C = 100mA, V_{CE} = 1.0V$		
Collector-Emitter Saturation Voltage	V _{CE(SAT)}		0.20 0.30	V	$I_C = 10$ mA, $I_B = 1.0$ mA $I_C = 50$ mA, $I_B = 5.0$ mA		
Base-Emitter Saturation Voltage	V _{BE(SAT)}	0.65	0.85 0.95	٧	$I_C = 10$ mA, $I_B = 1.0$ mA $I_C = 50$ mA, $I_B = 5.0$ mA		
SMALL SIGNAL CHARACTERISTICS							
Output Capacitance	C _{obo}	_	4.0	pF	$V_{CB} = 5.0V$, $f = 1.0MHz$, $I_E = 0$		
Input Capacitance	Cibo	_	8.0	pF	$V_{EB} = 0.5V$, $f = 1.0MHz$, $I_C = 0$		
Input Impedance	h _{ie}	1.0	10	kΩ			
Voltage Feedback Ratio	h _{re}	0.5	8.0	x 10 ⁻⁴	V _{CE} = 10V, I _C = 1.0mA,		
Small Signal Current Gain	h _{fe}	100	400	_	f = 1.0kHz		
Output Admittance	h _{oe}	1.0	40	μS			
Current Gain-Bandwidth Product	f _T	300	_	MHz	$V_{CE} = 20V, I_{C} = 10mA,$ f = 100MHz		
Noise Figure	NF	_	5.0	dB	$V_{CE} = 5.0V, I_{C} = 100\mu A,$ $R_{S} = 1.0k\Omega, f = 1.0kHz$		
SWITCHING CHARACTERISTICS		·					
Delay Time	t _d	_	35	ns	V _{CC} = 3.0V, I _C = 10mA,		
Rise Time	t _r		35	ns	$V_{BE(off)} = -0.5V, I_{B1} = 1.0mA$		
Storage Time	ts		200	ns	V _{CC} = 3.0V, I _C = 10mA,		
Fall Time	t _f	_	50	ns	$I_{B1} = I_{B2} = 1.0 \text{mA}$		

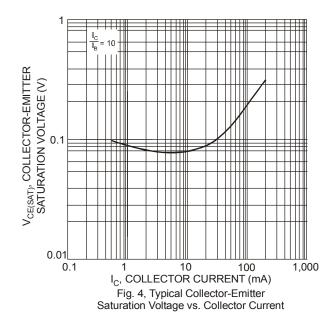
Notes: 6. Short duration pulse test used to minimize self-heating effect.

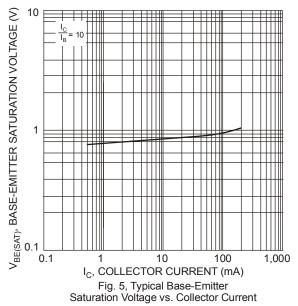










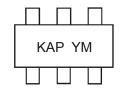


Ordering Information (Note 7)

Device	Packaging	Shipping			
MMDT3904V-7	SOT-563	3000/Tape & Reel			

Notes: 7. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



KAP = Product Type Marking Code YM = Date Code Marking Y = Year (ex: R = 2004) M = Month (ex: 9 = September)

Date Code Key

Year	2004	20	05	2006	2007	20	80	2009	2010	20	11	2012
Code	R		6	Т	U	\	/	W	Х	`	Y	Z
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



IMPORTANT NOTICE

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to any product herein. Diodes Incorporated does not assume any liability arising out of the application or use of any product described herein; neither does it convey any license under its patent rights, nor the rights of others. The user of products in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on our website, harmless against all damages.

LIFE SUPPORT

Diodes Incorporated products are not authorized for use as critical components in life support devices or systems without the expressed written approval of the President of Diodes Incorporated.